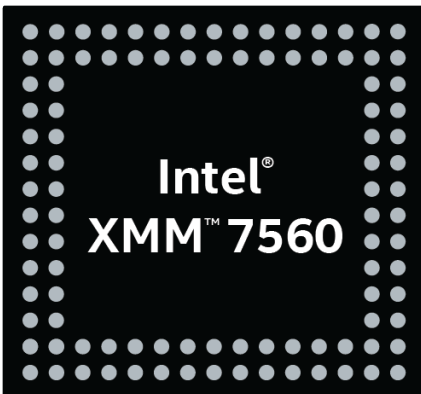


Intel® XMM™ 7560

LTE Advanced Pro modem delivering speeds exceeding 1Gbps for the next generation of advanced cellular devices



Single-SKU Global Coverage. Gigabit Speeds. 14nm for Slim, Powerful Designs.

Our fifth-generation LTE modem, the Intel XMM 7560 modem builds on a tradition of fast speeds, low latency, and radio innovation—offering gigabit speeds for the first time in a single, global SKU. The first of its kind to be designed via Intel's 14nm manufacturing process, it delivers high-speed LTE-advanced connectivity for quality voice calls and data-intensive applications, including video streaming, multi-player gaming, virtual reality applications and more.

The Intel XMM 7560 modem is fast—reaching blazing fast speeds exceeding 1Gbps in the downlink (Cat 16), and up to 225Mbps in the uplink (Cat 15)—meeting 3GPP Release 13 requirements. Beyond LTE, it also supports LAA (Licensed Assisted Access), providing enhanced flexibility and throughput. The modem's architecture is optimized to provide these services, while also ensuring in-device coexistence.

This modem was designed with the global manufacturer in mind. Not only does it support six modes of operation, it also provides 5x Carrier Aggregation for downlink of four non-contiguous bands up to 100MHz. In total, the Intel® SMARTi™ 7 RF transceiver and the Intel XMM 7560 platform are capable of up to 230 Carrier Aggregation combinations, covering every major operator.

The Intel SMARTi™ 7 transceiver offers industry-leading band density—supporting 35 bands simultaneously in a single SKU for true global mobile coverage. With 4x4 DL-MIMO and 256QAM, it's not just fast, it's agile—benefiting both manufacturers and carriers with gigabit speeds, delivered over mixed spectrum assets for performance and efficiency.

The Intel XMM 7560 modem is a competitive option for device manufacturers looking to quickly design and launch LTE devices in multiple market segments and geographies worldwide, and a strong addition to Intel's broad portfolio of connectivity solutions.

Product Features



Designed for Worldwide Mobility

- Industry-leading band density with support for more than 35 LTE bands simultaneously
- Global coverage with a single design SKU, built with Intel's 14nm process to meet 3GPP Rel-13 requirements
- 6-mode operation for global market, including LTE-FDD, LTE-TDD, TD-SCDMA, GSM/EDGE, UMTS/WCDMA, and CDMA/EVDO



Leading-edge Performance and Data Quality

- Blazing-fast LTE Advanced speeds exceeding 1Gbps download and 150 Mbps upload (225Mbps with a companion RF device)
- 5x Carrier Aggregation for DL of 4 non-contiguous bands up to 100MHz
- Carrier Aggregation supports all major carriers with 230 combinations
- 256QAM downlink and 64QAM uplink modulation schemes for better spectrum efficiency and higher data rate



Optimized Power Consumption

- Built on Intel's 14nm process, consuming less power than Intel's previous generation LTE Advanced modem



Enhanced Features

- Release 13 Enhanced Voice Service (EVS) to improve voice call performance with Network Assisted Interference Cancellation and Suppression (NAISC) support
- Enhanced dual-SIM including LTE/LTE, dual standby (eDSDS) enables multi-subscription support on a single device
- Supports 3.5GHz and 5GHz spectrum bands for LTE and WiFi Link Aggregation with LAA

Technical Specifications

Baseband	Intel® X-GOLD™ 756
Transceiver	Intel® SMARTi™ 7
Standards & Performance	3GPP Release 13 LTE FDD/TDD 1Gbps/150 Mbps LAA Support TD-SCDMA 2.8/2.2 Mbps, DC-HSPA+ Cat 24, 42Mbps DC-HSUPA Cat 8, 11.5Mbps
Transceiver Capabilities	LTE-FDD LTE-TDD UMTS/WCDMA TD-SCDMA CDMA/EVDO GSM/EDGE
Carrier Aggregation	LTE FDD/TDD/Hybrid DL 5CA UL 3CA
Modulation	LTE UL-64QAM; DL-256QAM
RF Bands	More than 35 LTE bands simultaneous; 3.5GHz/5GHz
SIM Support	Multi-SIM eDSDS/DSDA with 2G; WCDMA and LTE on 2nd SIM

For more information on Intel® Wireless products, visit:

<http://www.intel.com/modems>

